TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (L<sup>2</sup>-π-MOSV)

# **2SJ412**

# DC-DC Converter, Relay Drive and Motor Drive Applications

- 4-V gate drive
- Low drain-source ON resistance: RDS (ON) =  $0.15 \Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 7.7 \text{ S (typ.)}$
- Low leakage current:  $IDSS = -100 \mu A \text{ (max) (VDS} = -100 \text{ V)}$
- Enhancement mode:  $V_{th} = -0.8$  to -2.0 V ( $V_{DS} = -10$  V,  $I_{D} = -1$  mA)

### Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	-100	V	
Drain-gate voltage (R <sub>GS</sub> = 20 kΩ)		$V_{DGR}$	-100	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	I <sub>D</sub>	-16	А	
	Pulse (Note 1)	I <sub>DP</sub>	-64		
Drain power dissipation	n (Tc = 25°C)	P <sub>D</sub>	60	W	
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	292	mJ	
Avalanche current		I <sub>AR</sub>	-16	Α	
Repetitive avalanche e	energy (Note 3)	E <sub>AR</sub>	6	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55 to 150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	2.08	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	83.3	°C/W

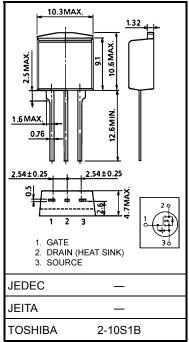
Note1: Ensure that the channel temperature does not exceed 150°C.

Note 2:  $V_{DD}$  = -25 V,  $T_{ch}$  = 25°C (initial), L = 1.84 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = -16 A

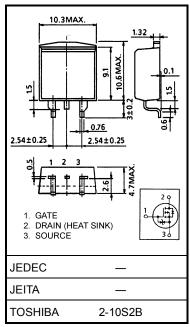
Note 3: Repetitive rating: pulse width limited by maximum junction temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.

Unit: mm



Weight: 1.5 g (typ.)



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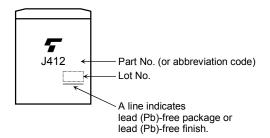
## Electrical Characteristics (Ta = 25°C)

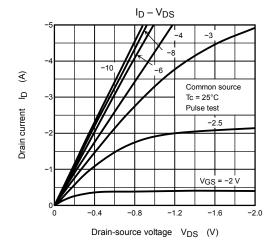
Chara	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Drain cut-off curre	ent	I <sub>DSS</sub>	V <sub>DS</sub> = -100 V, V <sub>GS</sub> = 0 V	_	_	-100	μΑ
Drain-source brea	akdown voltage	V (BR) DSS	I <sub>D</sub> = -10 mA, V <sub>GS</sub> = 0 V	-100	_	_	V
Gate threshold vo	oltage	V <sub>th</sub>	V <sub>DS</sub> = −10 V, I <sub>D</sub> = −1 mA	-0.8	_	-2.0	V
Cata aguras ON	raciatanaa	_	V <sub>GS</sub> = -4 V, I <sub>D</sub> = -6 A	_	0.25	0.32	
Gate-source ON resistance		R <sub>DS</sub> (ON)	V <sub>GS</sub> = -10 V, I <sub>D</sub> = -6 A	_	0.15	0.21	Ω
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -6 A	4.5	7.7	_	S
Input capacitance	•	C <sub>iss</sub>		-	1100	_	pF
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	210	_	pF
Output capacitance		C <sub>oss</sub>		_	440	_	pF
Switching time	Rise time	t <sub>r</sub>	V <sub>GS</sub> -10 V	_	18	_	
	Turn-on time	t <sub>on</sub>		_	30	_	
	Fall time	t <sub>f</sub>		_	18	_	ns
	Turn-off time	t <sub>off</sub>	Duty ≤ 1%, t <sub>w</sub> = 10 μs	ı	65	_	
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \approx -80 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -16 \text{ A}$	_	48		nC
Gate-source charge		Q <sub>gs</sub>		_	29		nC
Gate-drain ("miller") charge		Q <sub>gd</sub>		_	19	_	nC

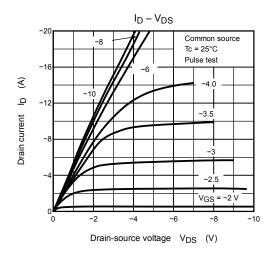
### **Source-Drain Rating and Characteristics (Ta = 25°C)**

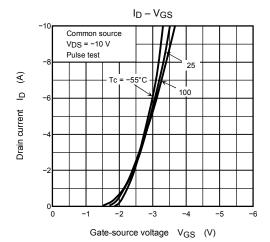
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	-16	А
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	-64	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = -16 A, V <sub>GS</sub> = 0 V	_	_	1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = -16 A, V <sub>GS</sub> = 0 V		160	_	ns
Reverse recovery charge	Q <sub>rr</sub>	dl <sub>DR</sub> /dt = 50 A/μs	_	0.5	_	μC

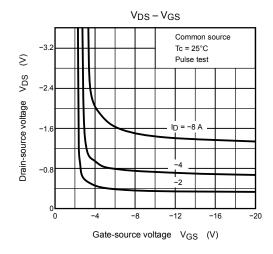
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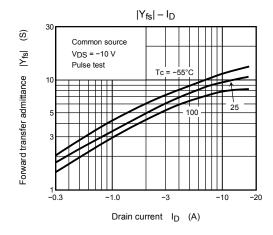


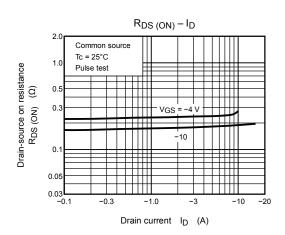


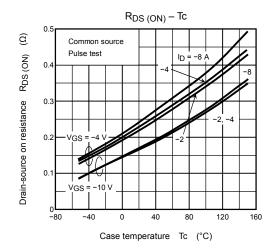


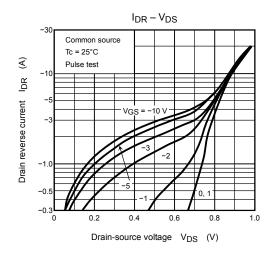


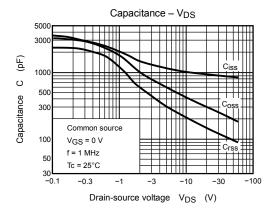


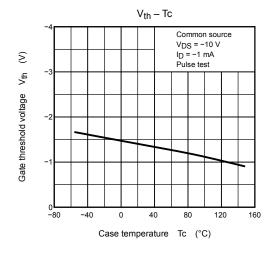


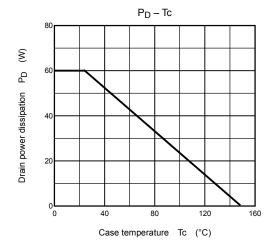


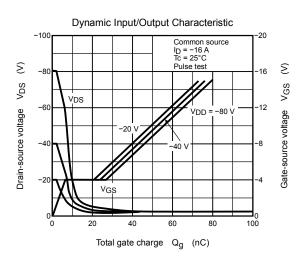




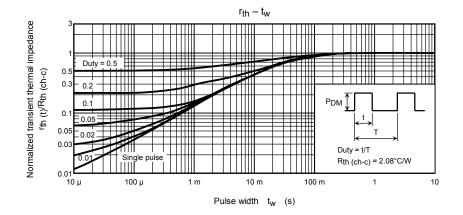


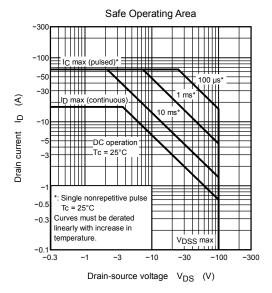


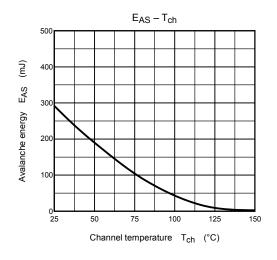


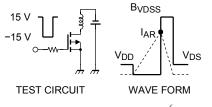


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$$R_G = 25 \Omega$$
  
 $V_{DD} = -25 \text{ V}, L = 1.84 \text{ mH}$   $E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$ 

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